

Title (en)

Additives for accelerator solution for electroless metal plating

Title (de)

Additive für Beschleunigerslösungen für die stromlose Metallplattierung

Title (fr)

Additifs pour solution accélératrice pour le dépôt chimique d'un métal

Publication

**EP 1281787 A2 20030205 (EN)**

Application

**EP 02255393 A 20020801**

Priority

JP 2001234424 A 20010802

Abstract (en)

Additives for accelerator solutions are provided which contain one or more accelerator solution suspension inhibiting compounds. By using accelerator solutions containing such additives in accelerator treatment processes for electroless copper plating methods, an increase in the turbidity of the accelerator solution can be prevented.

IPC 1-7

**C23C 18/28**; **C23C 18/16**

IPC 8 full level

**C23C 18/16** (2006.01); **C23C 18/28** (2006.01); **C23C 18/38** (2006.01)

CPC (source: EP KR)

**C23C 18/208** (2013.01 - EP); **C23C 18/285** (2013.01 - EP); **C23C 18/30** (2013.01 - EP); **C23C 18/38** (2013.01 - EP KR)

Cited by

US7198662B2; EP2524976A1; CN103534384A; EP3190209A1; US9822034B2; US10808047B2; WO2008098830A1; WO2012156162A3; WO2017118582A1

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**EP 02255393 A 20020801**; CN 02152914 A 20020802; JP 2001234424 A 20010802; KR 20020045745 A 20020802; TW 91117273 A 20020801